

Metal foil clad laminate for PCB(s) - has base of nonwoven glass fabric impregnated with resin contg. inorganic filler

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Abstract (Basic): JP 5261855 A

A part or whole of a base material is glass nonwoven fabric which is impregnated with resin contg. 60-80 wt. parts or less of inorganic filler with average dia. of 10 micron or less (pref. 5 micron or less) per 100 wt. parts of the resin.

USE/ADVANTAGE - For printed circuit boards. Smaller rate of expansion in thickness direction of the laminate.

In an example, a varnish, methylethylketone-methylglycol solution (resin solid content = 60 wt.%) of 100 wt. parts of Epicoat 1001 (YUKA SHELL KK), 4 wt. parts of dicyandiamide and 0.5 wt. parts of 2-ethyl-4-methylimidazole is prepared. 0.18 micron thick glass fabric is impregnated with the varnish and dried to skin prepreg. with 45 wt.% resin content. 80 wt. parts of talc with 5 micron dia. (NIPPON TALC KK) is added in the varnish to 100 wt. parts of resin solid. Glass nonwoven fabric (basis weight = 75 g/m²) is impregnated with the filler contg. varnish and dried to core prepreg. (resin content = 85 wt.%). Three sheets of core prepreg. skin prepreg. on each side and 18 microns thick copper foil on each outer surface are piled up and moulded at 170 deg. C, 60 kg/cm² for 90 min. to give 1.6 mm thick double copperclad laminate.

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Title Terms: METAL; FOIL; CLAD; LAMINATE; PCB; BASE; NONWOVEN; GLASS; FABRIC; IMPREGNATE; RESIN; CONTAIN; INORGANIC; FILL

Index Terms/Additional Words: PRINTED; CIRCUIT; BOARD

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